

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSB013NE2LXI	**Issued**	11. November 2019
MA#	MA000944588		
Package	MG-WDSON-2-8	**Weight***	83.36 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.882	4.66	4.66	46575	46575
leadframe	non noble metal	copper	7440-50-8	74.415	89.29	89.29	892741	892741
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.25		2534	
	noble metal	silver	7440-22-4	0.840	1.01	1.26	10077	12611
plating	non noble metal	nickel	7440-02-0	0.211	0.25	0.25	2534	2534
solder	non noble metal	copper	7440-50-8	0.011	0.01		132	
	noble metal	silver	7440-22-4	0.066	0.08		790	
	non noble metal	tin	7440-31-5	2.119	2.54	2.63	25416	26338
glue	plastics	acrylic resin	-	0.178	0.21		2138	
	noble metal	silver	7440-22-4	1.095	1.31	1.52	13136	15274
passivation	plastics	epoxy resin	-	0.327	0.39	0.39	3927	3927
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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